

Amendments to the Specification:

Please replace the paragraphs between page 5, line 17, and page 6, line 23, with the following amended paragraphs:

The auxiliary substrates 3 are provided by depositing ITO films on 1.1 mm thick sodalime glass substrates of 50 mm width and 270 mm length. The ITO film is patterned by a known photolithography. The ITO pattern 19 is then coated with Ni and thereafter with Au respectively by plating. The pattern includes contacts with which IC chips for producing driving signals are electrically connected. The connection of the chips and the contacts are made by applying Au bumps to contact pads of the chips, dripping a curable adhesive onto the rare surfaces of the chips and, after aligning the pads and the contacts of the substrate, exposing the adhesive to ultraviolet light under pressure of 95 g per bump at 150 °C for three minutes in order to harden the adhesive and fix the chips to the substrate. Then, the driving circuits as manufactured as above on the substrate are tested at the outer leads with which the electrodes of a liquid crystal display should be connected for supplying driving signals in order to eliminate substrates carrying inoperative circuits.

The electric connection between the first and second substrates 1 and 2 and the counterpart auxiliary substrates 3 respectively are done as follows. The extended inside surfaces of the first substrates 1 on which terminals of the respective electrodes are exposed are coated, by means of a dispenser, with an anisotropic conductive film. The adhesive film is made from a UV light curable adhesive 8 in which a number of resilient fine conductive particles 6 and hard particles 7 whose diameter is slightly smaller than that of the resilient particles are dispersed. The resilient particles are made from 7.5 µm thick polystyrene spheres plated with a 1000 angstroms thick Au film. The hard particles are made from 5 µm thick SiO₂ spheres. The weight proportion among the adhesive, the resilient particles and the hard particles is 107:14:1. Then, the

first substrate 1 and the auxiliary substrates 3 are joined with the adhesive therebetween in order that the [[the]] terminals of the first substrate 1 and the corresponding contacts of the auxiliary substrate 3 are aligned to each other, and exposed to UV light for 3 minutes under pressure of about 2.4 kg/cm^2 . The hard particles are included in order to prevent the conductive resilient particles from being destroyed under excess pressure. The second substrate 2 is electrically connected with the other auxiliary substrate 3' in the same manner. When displays as produced as above were subjected to a thermal shock test at -30°C and at 70°C respectively for an hour, all the sample displays were maintained operable.